General Purpose Transistor

NPN Silicon

Features

• These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V _{CEO}	32	Vdc
Collector - Base Voltage	V _{CBO}	32	Vdc
Emitter - Base Voltage	V _{EBO}	5.0	Vdc
Collector Current – Continuous	I _C	100	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) TA = 25°C	P _D	225	mW
Derate above 25°C		1.8	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate (Note 2), TA = 25°C	P _D	300	mW
Derate above 25°C		2.4	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

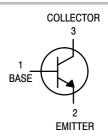
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.
- 2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.



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SOT-23 (TO-236AB) CASE 318 STYLE 6

MARKING DIAGRAM



D3 = Specific Device Code

M = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
BCW33LT1G	SOT-23 (Pb-Free)	3000/Tape & Reel
BCW33LT3G	SOT-23 (Pb-Free)	10,000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector – Emitter Breakdown Voltage ($I_C = 2.0 \text{ mAdc}, I_B = 0$)	V _{(BR)CEO}	32	_	Vdc
Collector – Base Breakdown Voltage ($I_C = 10 \mu Adc$, $I_B = 0$)	V _{(BR)CBO}	32	=	Vdc
Emitter – Base Breakdown Voltage ($I_E = 10 \mu Adc, I_C = 0$)	V _{(BR)EBO}	5.0	-	Vdc
Collector Cutoff Current $(V_{CB} = 32 \text{ Vdc}, I_E = 0)$ $(V_{CB} = 32 \text{ Vdc}, I_E = 0, T_A = 100^{\circ}\text{C})$	Ісво	_ _	100 10	nAdc μAdc
ON CHARACTERISTICS				
DC Current Gain ($I_C = 2.0 \text{ mAdc}, V_{CE} = 5.0 \text{ Vdc}$)	hFE	420	800	-
Collector – Emitter Saturation Voltage ($I_C = 10 \text{ mAdc}$, $I_B = 0.5 \text{ mAdc}$)	V _{CE(sat)}	-	0.25	Vdc
Base – Emitter On Voltage (I _C = 2.0 mAdc, V _{CE} = 5.0 Vdc)	V _{BE(on)}	0.55	0.70	Vdc
SMALL-SIGNAL CHARACTERISTICS	!	•		
Output Capacitance (V _{CB} = 10 Vdc, I _E = 0, f = 1.0 MHz)	C _{obo}	-	4.0	pF
Noise Figure $(V_{CE}=5.0~Vdc,~I_{C}=0.2~mAdc,~R_{S}=2.0~k\Omega,~f=1.0~kHz,~BW=200~Hz)$	NF	-	10	dB

EQUIVALENT SWITCHING TIME TEST CIRCUITS

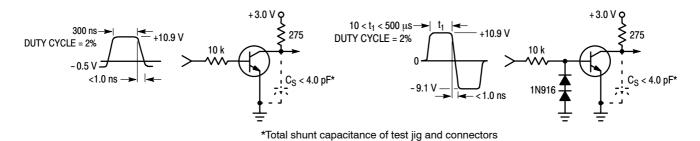


Figure 1. Turn-On Time

Figure 2. Turn-Off Time

TYPICAL NOISE CHARACTERISTICS

 $(V_{CE} = 5.0 \text{ Vdc}, T_A = 25^{\circ}C)$

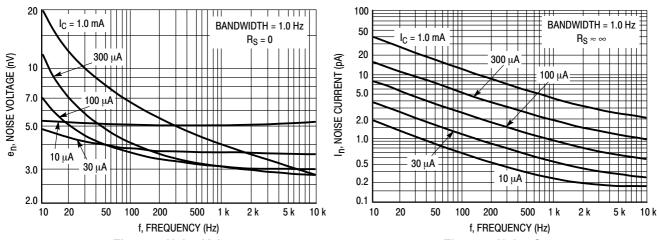


Figure 3. Noise Voltage

Figure 4. Noise Current

NOISE FIGURE CONTOURS

 $(V_{CE} = 5.0 \text{ Vdc}, T_A = 25^{\circ}C)$

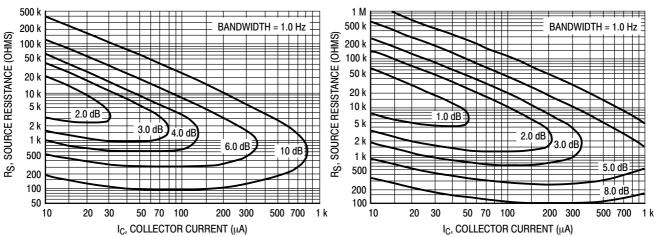


Figure 5. Narrow Band, 100 Hz

Figure 6. Narrow Band, 1.0 kHz

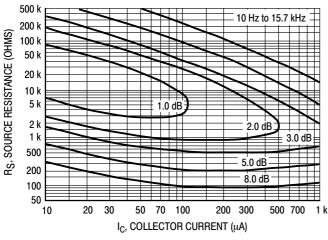


Figure 7. Wideband

Noise Figure is defined as:

$$NF = 20 \log_{10} \left(\frac{e_n^2 + 4KTR_S + I_n^2 R_S^2}{4KTR_S} \right)^{1/2}$$

en = Noise Voltage of the Transistor referred to the input. (Figure 3)

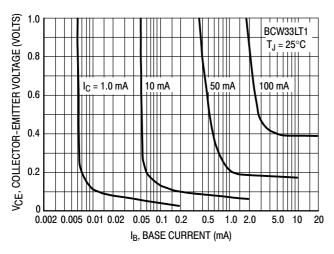
In = Noise Current of the Transistor referred to the input. (Figure 4)

... K = Boltzman's Constant (1.38 x 10⁻²³ j/°K)

T = Temperature of the Source Resistance (°K)

R_S = Source Resistance (Ohms)

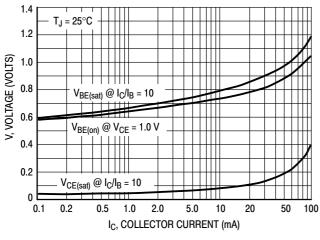
TYPICAL STATIC CHARACTERISTICS



100 $T_A = 25$ °C PULSE WIDTH = 300 μ s DUTY CYCLE ≤ 2.0 % $I_B = 500 \mu A$ C, COLLECTOR CURRENT (mA) 400 μΑ 80 300 μΑ 60 200 μΑ 40 100 μΑ 20 0 5.0 10 35 0 15 20 40 V_{CE}, COLLECTOR-EMITTER VOLTAGE (VOLTS)

Figure 8. Collector Saturation Region

Figure 9. Collector Characteristics



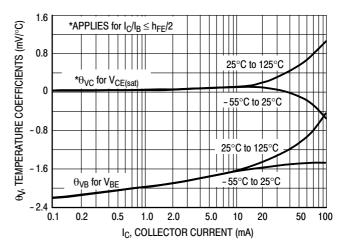
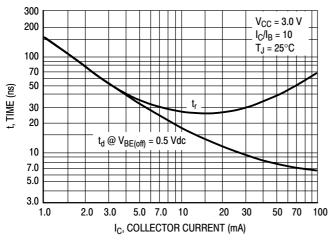


Figure 10. "On" Voltages

Figure 11. Temperature Coefficients



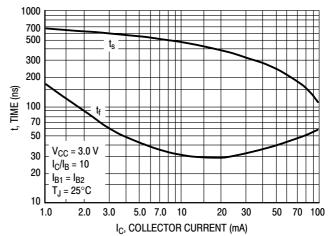
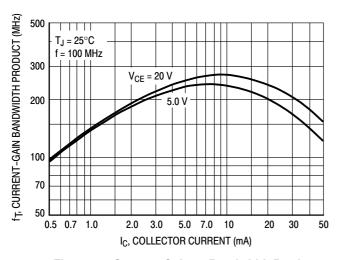


Figure 12. Turn-On Time

Figure 13. Turn-Off Time

TYPICAL DYNAMIC CHARACTERISTICS



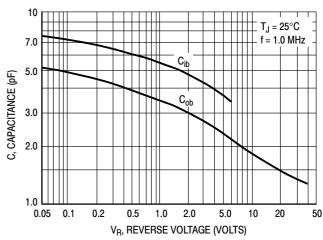


Figure 14. Current-Gain — Bandwidth Product

Figure 15. Capacitance

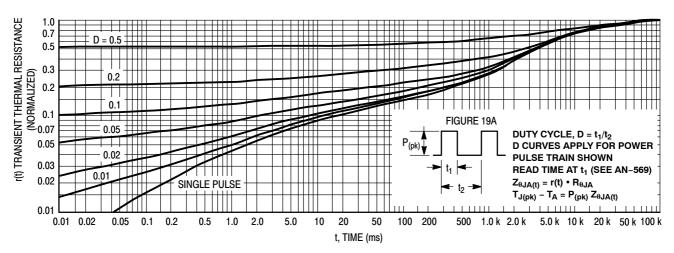


Figure 16. Thermal Response

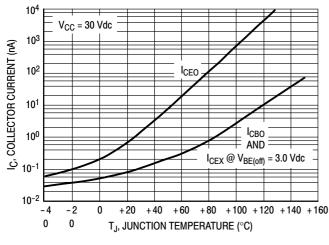


Figure 16A.

DESIGN NOTE: USE OF THERMAL RESPONSE DATA

A train of periodical power pulses can be represented by the model as shown in Figure 16A. Using the model and the device thermal response the normalized effective transient thermal resistance of Figure 16 was calculated for various duty cycles.

To find $Z_{\theta JA(t)},$ multiply the value obtained from Figure 16 by the steady state value $R_{\theta JA}.$

Example:

The MPS3904 is dissipating 2.0 watts peak under the following conditions:

$$t_1 = 1.0 \text{ ms}, t_2 = 5.0 \text{ ms}. (D = 0.2)$$

Using Figure 16 at a pulse width of 1.0 ms and D = 0.2, the reading of r(t) is 0.22.

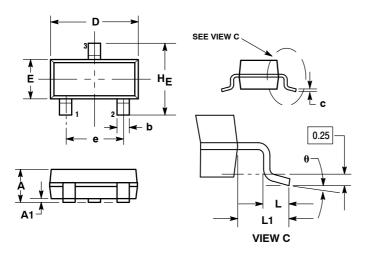
The peak rise in junction temperature is therefore

$$\Delta T = r(t) \times P_{(pk)} \times R_{\theta JA} = 0.22 \times 2.0 \times 200 = 88^{\circ}C.$$

For more information, see AN-569.

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AN**



NOTES:

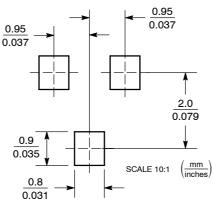
- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982.
- Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD
 FINISH THICKNESS. MINIMUM LEAD
 THICKNESS IS THE MINIMUM THICKNESS OF
- 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 6:

- PIN 1. BASE
 - 2. **EMITTER**
 - 3. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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